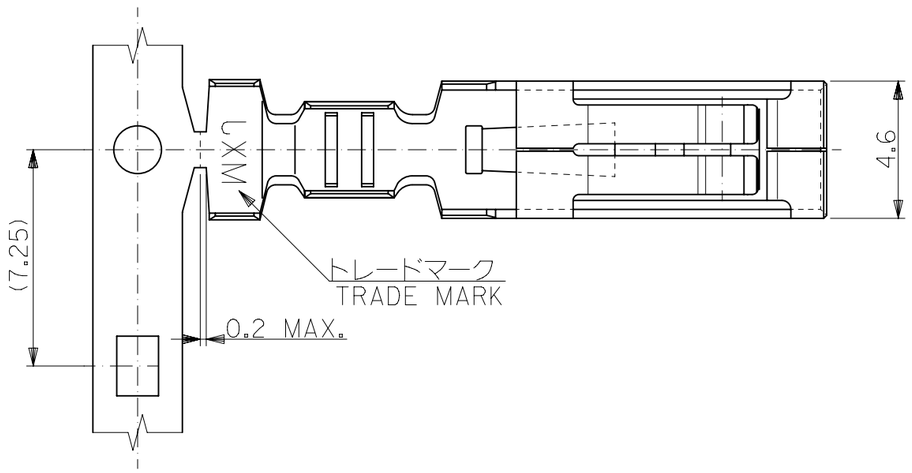
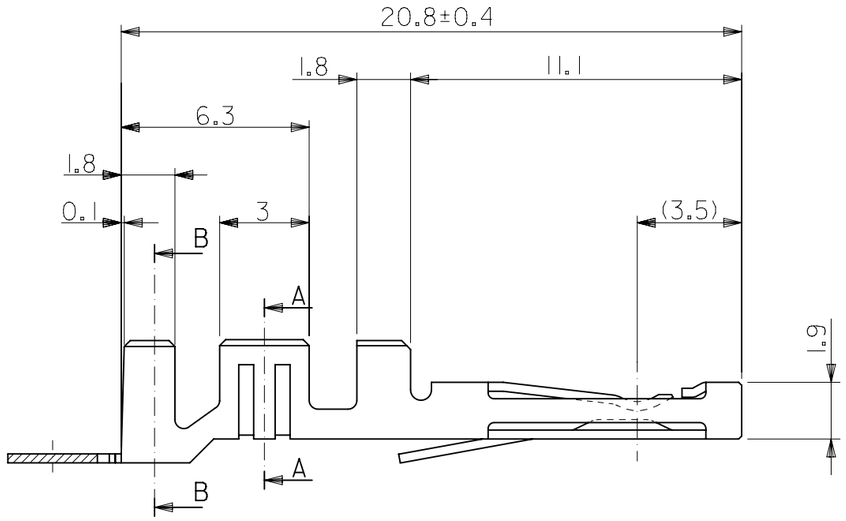
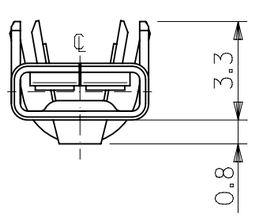
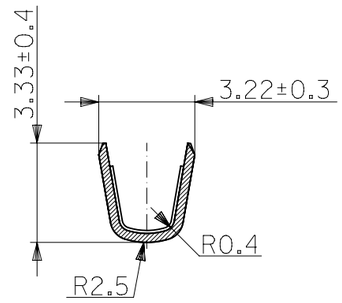
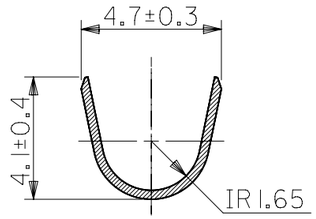








A-A



B-B

注)
NOTES;

1. 材質
   MATERIAL
   銅合金　(板厚：0．3)
   COPPER ALLOY(THICKNESS : 0.3)
2. メッキ仕様
   TERMINAL PLATING
   接点部　：　金メッキ 0.25 μm　ＭＩＮ．
   CONTACT AREA : GOLD　0.25 MICROMETER MIN.
   圧着部　：　錫メッキ 1.0μm　ＭＩＮ．
   CRIMP AREA : TIN 1.0 MICROMETER MIN.
   下地メッキ　：　ニッケルメッキ 2.0 μm　ＭＩＮ．
   UNDER PLATE : NICKEL 2.0 MICROMETER MIN.
3. 適用電線範囲：ＵＬ２５１７，ＡＷＧ #１６
   APPLICABLE WIRE RANGE : UL2517 , AWG #16
4. 被覆外径　：ø2.2～ø2.7
   INSULATION EXTERNAL DIA : ø2.2～ø2.7
5. 適用ハウジングアッセンブリ：　51195 シリーズ
   APPLICABLE HOUSING ASS'Y : 51195 SERIES
6. 本製品は５９３１９－＊＊９０の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 59319-**90.

連鎖状 CHAIN	59319-0028	59319-**28
端子形状 TERMINAL CONFIGURATION	MATERIAL No.	MODEL NO.
	DIMENSIONS:	SHT / REV

MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		
FINISH 仕上げ	10 UNDER 未満	±0.2	
WIRE RANGE 適用電線範囲	10 OVER 以上 30 UNDER 未満	±0.25	
INS. RANGE 被覆外径	30 OVER 以上	±0.3	
	ANGLE 角度	±3°	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS: mm　SCALE: 1:1

GENERAL TOLERANCES (UNLESS SPECIFIED)

	MM	INCH
4 PLACES	±	±
3 PLACES	±	±
2 PLACES	±	±
1 PLACE	±	±
0 PLACES	±	±
ANGULAR TOL	± °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

CURRENT REV DESC: RETRACTED AS PER THE REQUEST CASE #01114726

EC NO: 831459
DRWN: VISHAH2 2025/07/21
CHK'D: GB 2025/08/13
APPR: GB 2025/08/13

INITIAL REVISION:
DRWN: Y.WADA 2004/03/29
APPR: M.SASAO 2004/03/29

molex

POWER REC CRIMP TERM
-LEAD FREE-

PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER	DOC TYPE	DOC PART	REVISION
SD-59319-002	PSD	001	C

THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER	CUSTOMER	SHEET NUMBER
	B-SIZE	59319	SEE CHART	GENERAL MARKET	1 OF 1

DOCUMENT STATUS	P1	RELEASE DATE	2025/08/13 13:39:30

FORMAT: Eng-legal-portrait-prod-B
REVISION: E
DATE: 2020/01/14